



Typical Assembly recommendations for Open Cavity Plastic Packages

- 1) Die Thickness: 12 – 15 mils
- 2) Die Attach Method: Epoxy
- 3) Wire Bond:

Thermal Compression Au Bonding

- a) 0.001” to 0.0013” Diameter Wire
- b) Ceramic capillary with 20° taper
- c) Maximum package temperature during bonding: 150°C
- d) Minimum wire length: 15 mils / nominal 25 mils

Al Wedge Bonding

- a) 0.001” to 0.00125” Diameter Wire
- b) 60° or 90° wire feed machine (depending on available bond area)
- c) Maximum package temperature during bonding: Room Temperature
- d) Minimum wire length: 15 mils / nominal 25 mils

- 4) Seal Types:
 - a) Lid (plastic or ceramic)
 - b) Tape
 - c) Glob Top